

## **Notification about the transfer of the semiconductor business**

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

**Nuvoton Technology Corporation Japan**

# ADVANCE INFORMATION

## FJ4B0425ZL

### Single P-channel MOS FET

#### ■ Features

- Drain-source On-state Resistance :  $R_{DS(on)}$  typ. = 30 m $\Omega$  (  $V_{GS} = -10$  V )
- CSP( Chip Size Package )
- Halogen-free / RoHS compliant ( EU RoHS / UL-94 V-0 / MSL : Level 1 )
- Automotive grade

#### ■ Marking Symbol : 2M

#### ■ Packaging

Embossed type ( Thermo-compression sealing ) : 10,000 pcs / reel ( standard )

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Drain-source Voltage	VDS	-40	V
Gate-source Voltage	VGS	-20 / +10	V
Drain Current	DC	ID <sup>*1</sup>	-3.4
		ID <sup>*2</sup>	-5.3
		ID <sup>*3</sup>	-7.1
	Pulsed <sup>*4</sup>	IDp	-42.4
Total Power Dissipation	PD <sup>*1</sup>	0.42	W
	PD <sup>*2</sup>	1.00	
	PD <sup>*3</sup>	1.79	
Operating Junction and Storage Temperature Range	Tj, Tstg	-55 to +150	°C

#### ■ Thermal Characteristics $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Thermal Resistance ( ch-a )	Rth1 <sup>*1</sup>	300	°C / W
	Rth2 <sup>*2</sup>	125	
	Rth3 <sup>*3</sup>	70	

Note \*1 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ).

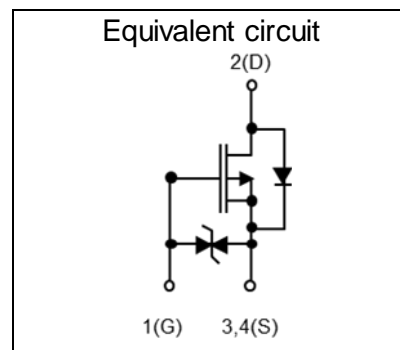
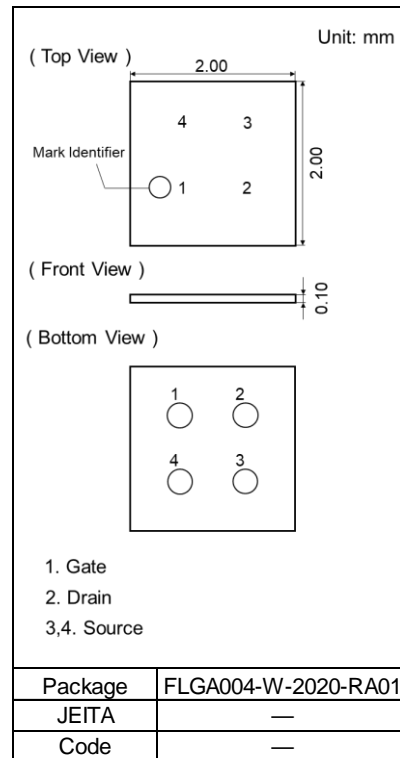
FR4 board partially covered with copper pad ( 65.2 mm<sup>2</sup> area, 35  $\mu$ m thickness ).

\*2 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ).

FR4 board fully covered with copper pad ( 616 mm<sup>2</sup> area, 35  $\mu$ m thickness ).

\*3 Mounted on ceramic board ( 70 mm × 70 mm × t1.0 mm ).

\*4 t = 10  $\mu$ s, Duty Cycle  $\leq$  1 %.



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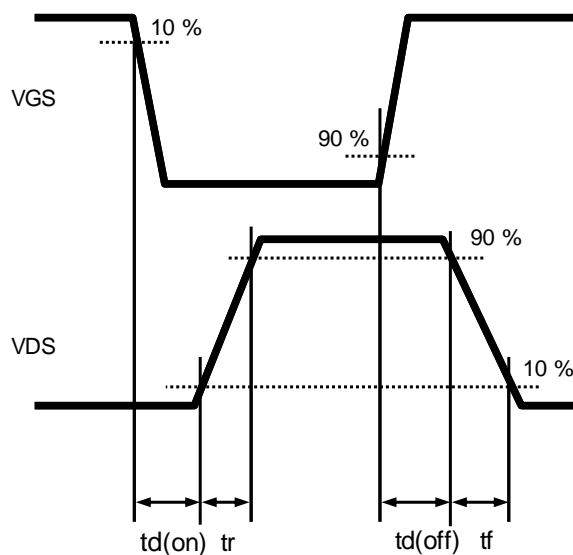
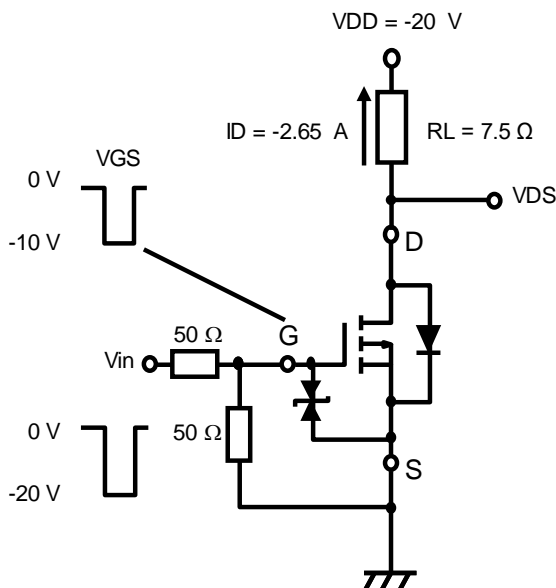
## ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0 V	-40			V
Zero Gate Voltage Drain Current	IDSS	VDS = -40 V, VGS = 0 V			-1	μA
Gate-source Leakage Current	IGSS	VGS = -16 V, VDS = 0 V			-10	μA
		VGS = +8 V, VDS = 0 V			10	
Gate-source Threshold Voltage	Vth	ID = -11.2 mA, VDS = -10 V	-1		-3	V
Drain-source On-state Resistance	RDS(on)1	ID = -2 A, VGS = -10 V	21	30	35	mΩ
	RDS(on)2	ID = -2 A, VGS = -4.5 V	24	35	60	
Body Diode Forward Voltage	VF(s-d)	IF = -2 A, VGS = 0 V		-0.77	-1.2	V
Input Capacitance *1	Ciss	VDS = -20 V, VGS = 0 V f = 1 MHz		3100		pF
Output Capacitance *1	Coss			200		
Reverse Transfer Capacitance *1	Crss			190		
Turn-on Delay Time *1,*2	td(on)	VDD = -20 V, VGS = 0 to -10 V		20		ns
Rise Time *1,*2	tr	ID = -2.65 A		30		
Turn-off Delay Time *1,*2	td(off)	VDD = -20 V, VGS = -10 to 0 V		220		
Fall Time *1,*2	tf	ID = -2.65 A		90		
Total Gate Charge *1	Qg1	VDD = -20 V, VGS = -4.5 V ID = -5.3 A		28		nC
	Qg2			58		
Gate-source Charge *1	Qgs	VDD = -20 V, VGS = -10 V ID = -5.3 A		8		
Gate-drain Charge *1	Qgd			11		

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

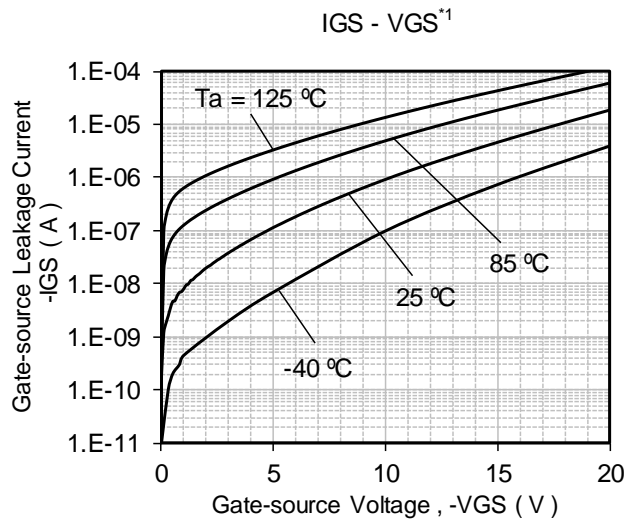
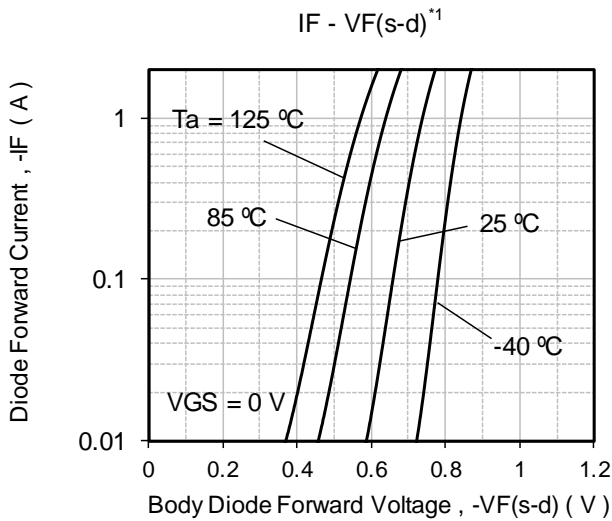
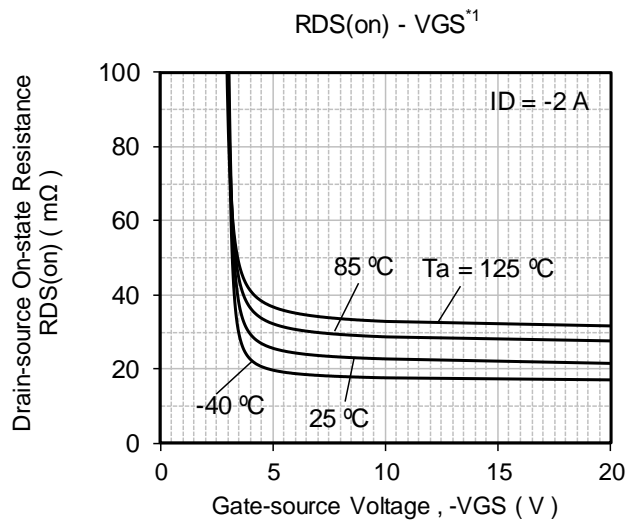
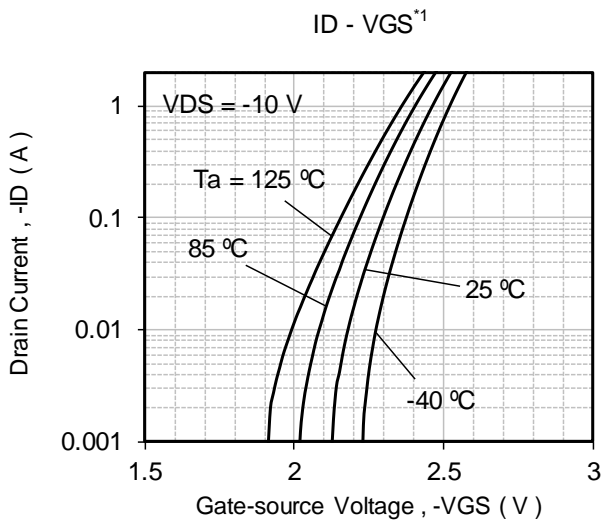
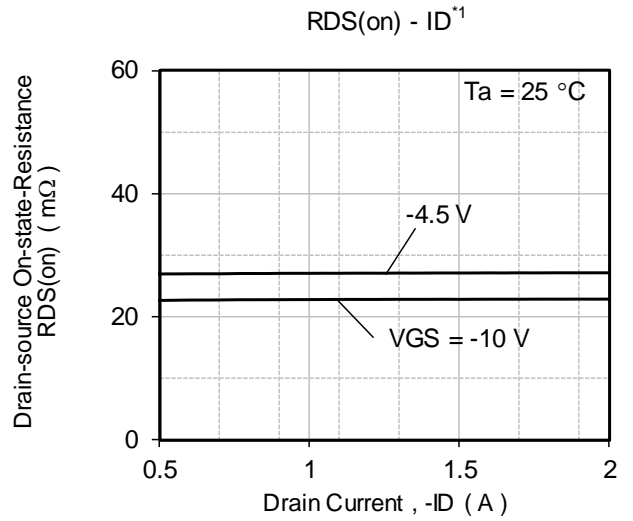
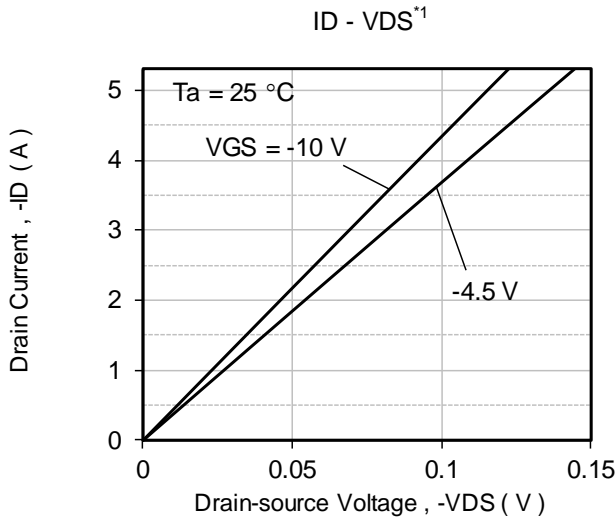
\*1 Guaranteed by design, not subject to production testing.

\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time.



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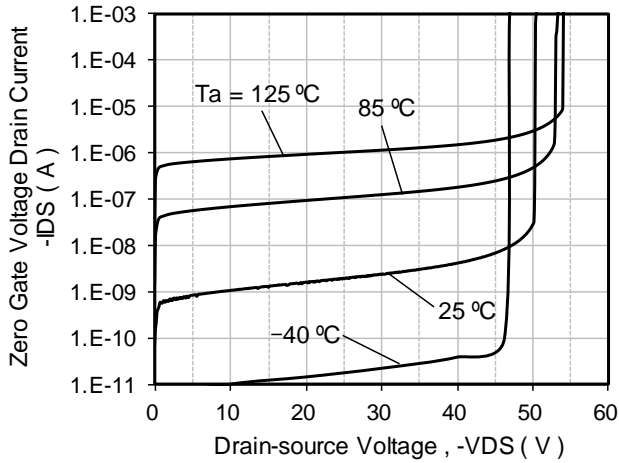
## Technical Data (reference)



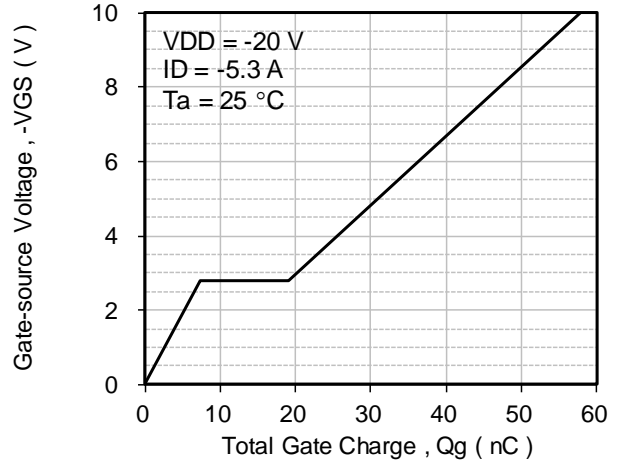
# ADVANCE INFORMATION

## Technical Data ( reference )

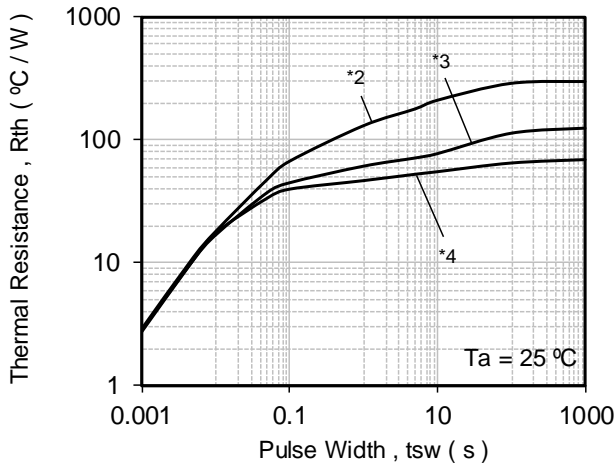
IDS - VDS<sup>\*1</sup>



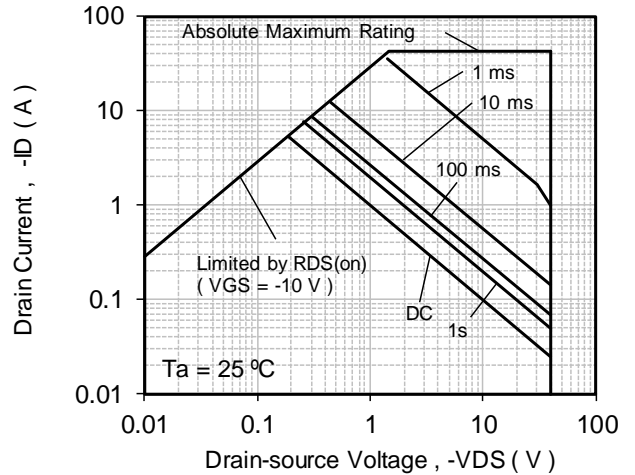
Dynamic Input / Output Characteristics



Rth - tsw



Safe Operating Area<sup>\*3</sup>

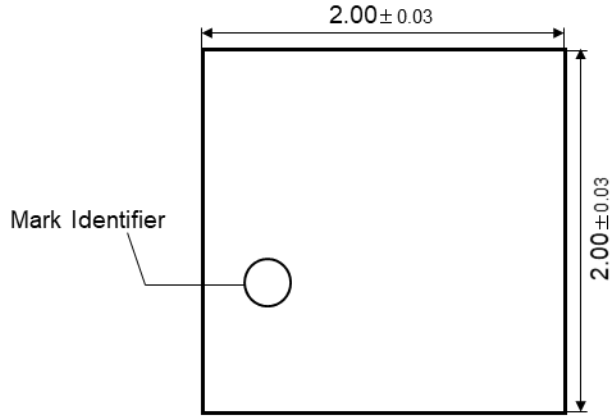


Note

- \*1 Pulse measurement.
- \*2 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ).  
FR4 board partially covered with copper pad ( 65.2 mm<sup>2</sup> area, 35 μm thickness ).
- \*3 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ).  
FR4 board fully covered with copper pad ( 616 mm<sup>2</sup> area, 35 μm thickness ).
- \*4 Mounted on ceramic board ( 70 mm × 70 mm × t1.0 mm ).

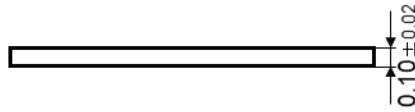
# ADVANCE INFORMATION

## ■ Outline ( Top View )

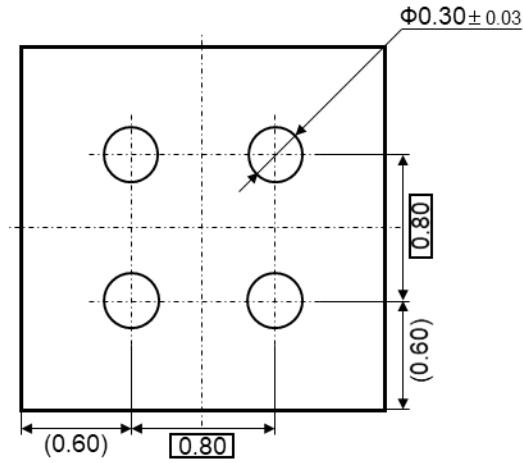


Unit: mm

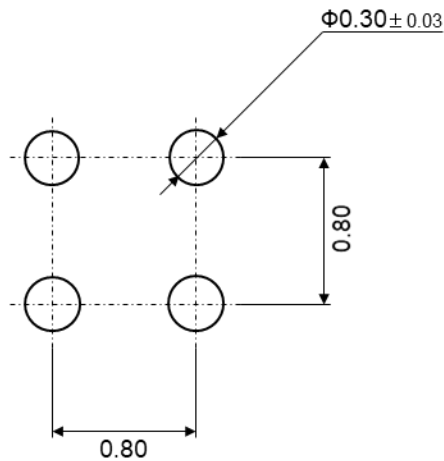
## ( Front View )



## ( Bottom View )



## ■ Land & Stencil Pattern ( reference )



Unit: mm

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